Toughened Structural Adhesive Cures at Room Temperature

Formulated for structural applications in extreme environments with temperatures from -80 to 425°F, Master Bond Supreme 33 has superior resistance to thermal cycling, thermal shock, and impact. This toughened, two-component epoxy offers high structural bond strength to a wide variety of substrates including metals, glass, ceramics, wood, vulcanized rubbers, and many plastics. Supreme 33 also resists chemicals including water, oil, and many organic solvents.

Supreme 33 has a mix ratio of 100 to 70 by weight or 1 to 1 by volume. It cures conveniently at room temperature in 48 to 72 hours. For optimal performance, the suggested schedule is curing overnight at room temperature followed by two to three hours at 150 to 200°F. This 100% reactive epoxy does not contain any solvents or diluents, has exceptional dimensional stability and features very low shrinkage upon cure.

It produces high performance bonds, boasting a shear strength over 2,500 psi, a tensile shear strength greater than 7,500 psi, and a T-peel strength exceeding 15 pli. With a volume resistivity of 10^{14} ohm-cm, a dielectric strength over 400 volts/mil, and a dielectric constant of 3.8 at 75°F, Supreme 33 is an outstanding electrical insulator. Supreme 33 is also available in a non-drip version called Supreme 33ND.

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